



## Material Content Data Sheet



Sales Product Name	TLE7278-2G V50			Issued		11. December 2019		
MA#	MA003438460							
Package	PG-DSO-14-30			Weight*		143.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.362	1.65	1.65	16506	16506
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8435	
	non noble metal	copper	7440-50-8	49.007	34.25	35.14	342491	351453
wire	noble metal	gold	7440-57-5	0.302	0.21	0.21	2113	2113
encapsulation	organic material	carbon black	1333-86-4	0.173	0.12		1211	
	plastics	epoxy resin	-	7.969	5.57		55693	
	inorganic material	silicondioxide	60676-86-0	78.479	54.85	60.54	548459	605363
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8569	8569
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7197	7197
glue	plastics	acrylic resin	-	0.277	0.19		1936	
	noble metal	silver	7440-22-4	0.982	0.69	0.88	6863	8799
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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